





P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(on)}	I _D T _A = +25°C
-20V	5Ω @ V _{GS} = -4.5V	-200mA
	7Ω @ V _{GS} = -2.5V	-170mA
	10Ω @ V _{GS} = -1.8V	-140mA
	15Ω @ V _{GS} = -1.5V	-50mA

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- **Power Management Functions**

Features and Benefits

- P-Channel MOSFET
- Low On-Resistance
- Very Low Gate Threshold Voltage V_{GS(TH)}
- Low Input Capacitance
- Fast Switching Speed
- Ultra-Small Surfaced Mount Package
- Ultra-Low Package Profile, 0.4mm Maximum Package Height
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

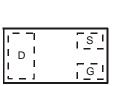
- Case: X2-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208@4
- Weight: 0.001 grams (Approximate)



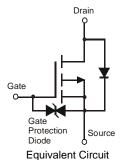




Bottom View



Top View Internal Schematic



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP210DUFB4-7	X2-DFN1006-3	3,000/Tape & Reel
DMP210DUFB4-7B	X2-DFN1006-3	10.000/Tape & Reel

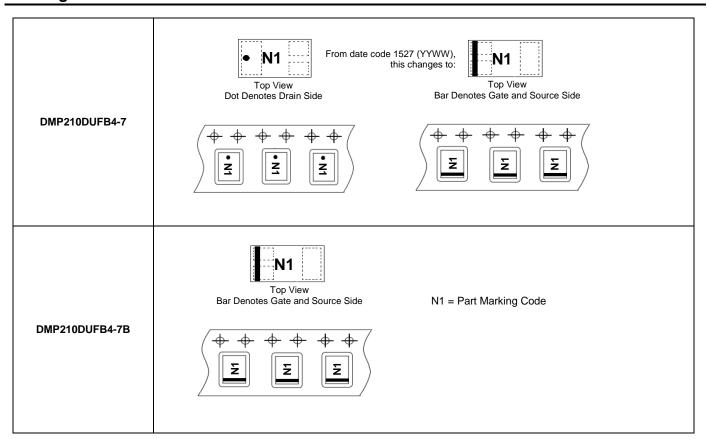
Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.



Marking Information





Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage	V_{DSS}	-20	V		
Gate-Source Voltage	V_{GSS}	±10	V		
Continuous Drain Current (Note 5) V _{GS} = -4.5V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	ID	-200 -160	mA
Continuous Drain Current (Note 5) V _{GS} = -1.8V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-140 -110	mA
Pulsed Drain Current	$T_P = 10$	μs	I _{DM}	-600	mA

Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_{D}	350	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

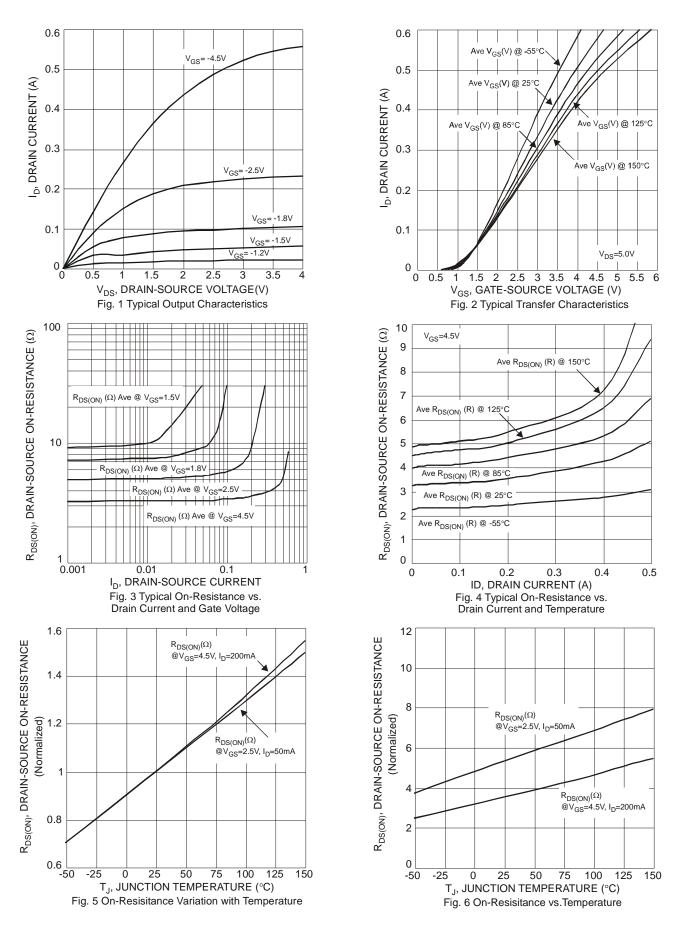
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 6)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	1	_	_	-100	nA	$V_{DS} = -16V, V_{GS} = 0V$	
Zelo Gate Voltage Dialii Culterit	I _{DSS}	_	_	-50	nA	$V_{DS} = -5.0V, V_{GS} = 0V$	
				±100	nA	$V_{GS} = \pm 5.0V, V_{DS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±1	μA μA	$V_{GS} = \pm 8.0V, V_{DS} = 0V$	
				±10		$V_{GS} = \pm 10.0 V, V_{DS} = 0 V$	
ON CHARACTERISTICS (Note 6)							
Gate Threshold Voltage @T _J =	+25°C V _{GS(th)}	-0.5	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
Gate Threshold Voltage (Note 7) @TJ	= 0°C	-0.55	_	-1.05			
@T _J =	= +85°C V _{GS(th)}	-0.40	_	-0.90	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
@T _J =	+100°C	-0.35	_	-0.85			
		_	_	5		$V_{GS} = -4.5V, I_D = -100mA$	
		_	_	7	Ω	$V_{GS} = -2.5V, I_D = -50mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	_	10		$V_{GS} = -1.8V, I_D = -20mA$	
			_	15		$V_{GS} = -1.5V, I_D = -10mA$	
		_	20	_		$V_{GS} = -1.2V, I_D = -1mA$	
Forward Transfer Admittance	Y _{fs}	200	_	_	mS	$V_{DS} = -10V, I_{D} = -200mA$	
Diode Forward Voltage (Note 5)	V_{SD}	-0.5	_	-1.2	V	$V_{GS} = 0V, I_{S} = -115mA$	
DYNAMIC CHARACTERISTICS (Note 7)							
Input Capacitance	C _{iss}	_	13.72	175	pF	151/1/ 01/	
Output Capacitance	Coss	_	4.01	30	pF	$V_{DS} = -15V, V_{GS} = 0V$ -f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}		2.34	20	pF	1 = 1.0WHZ	
SWITCHING CHARACTERISTICS (Note 7)							
Turn-On Delay Time	t _{d(on)}	_	7.7	_			
Rise Time	t _r		19.3	_	ns	$V_{GS} = -4.5V, V_{DD} = -15V$ $I_{D} = -180\text{mA}, R_{G} = 2.0\Omega$	
Turn-Off Delay Time	t _{d(off)}		25.9	_	115		
Fall Time	t _f		31.5	_			

Notes:

- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.6. Short duration pulse test used to minimize self-heating effect.7. Guaranteed by design. Not subject to production testing.







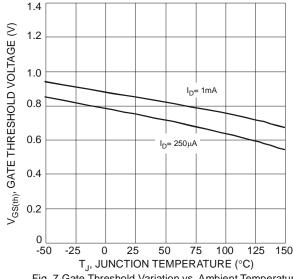
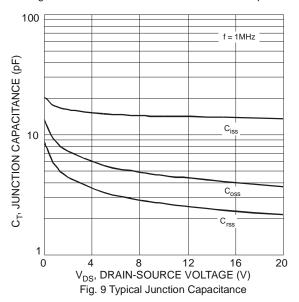
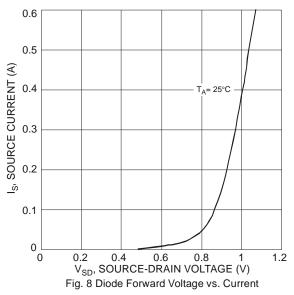


Fig. 7 Gate Threshold Variation vs. Ambient Temperature





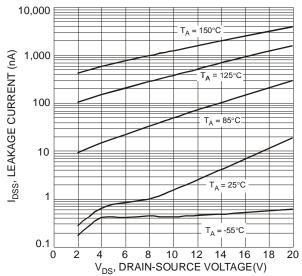


Fig. 10 Typical Drain-Source Leakage Current vs. Voltage

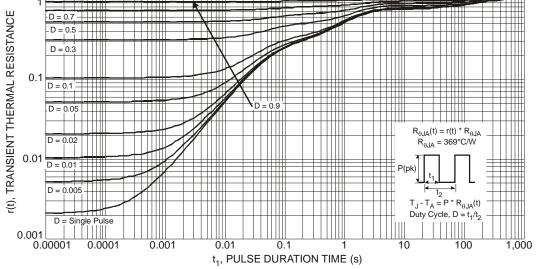
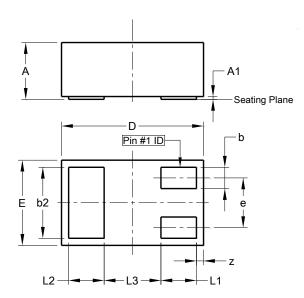


Fig. 11 Transient Thermal Response



Package Outline Dimensions

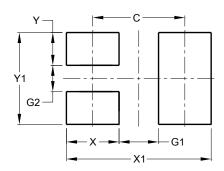
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



X2-DFN1006-3					
Dim	Min	Max	Тур		
Α	_	0.40	_		
A 1	0.00	0.05	0.03		
b	0.10	0.20	0.15		
b2	0.45	0.55	0.50		
D	0.95	1.05	1.00		
Е	0.55	0.65	0.60		
е	-		0.35		
L1	0.20	0.30	0.25		
L2	0.20	0.30	0.25		
L3	-		0.40		
Z	0.02	0.08	0.05		
All Dimensions in mm					

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	0.70		
G1	0.30		
G2	0.20		
Х	0.40		
X1	1.10		
Y	0.25		
Y1	0.70		



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